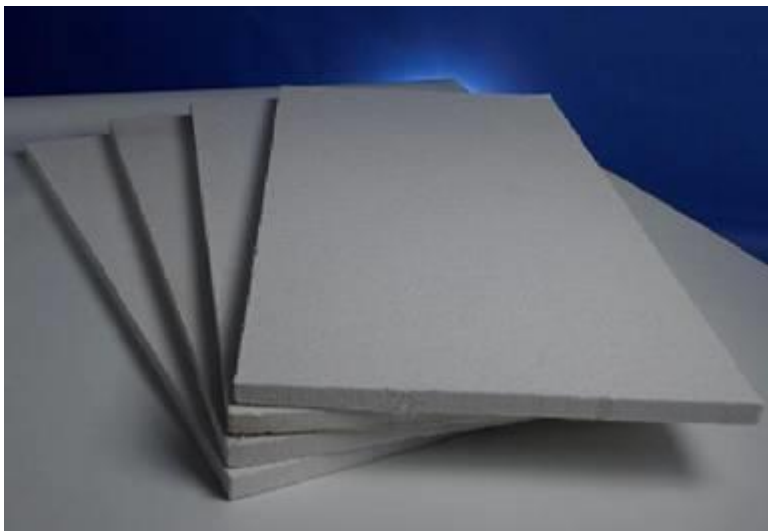


CERAMIC FIBRE HIGH TEMPERATURE BOARDS

Murugappa Morgan Thermal Ceramics Ltd., Associate company of Murugappa Group



TYPE: Rigid High temperature board based on refractory fibres

Classification temperature:

M – 1600 : 1600 ° C
L – 1600 : 1600 ° C

DESCRIPTION

Ceramic fibre boards are rigid self supporting insulating product manufactured from Refractory fibres. Ceramic fibre boards are designed for use in application conditions requiring superior insulating properties combined with high rigidity and mechanical strength at high temperature

AVAILABILITY

Standard sizes: 500 mm width X 1000 mm length

FEATURES

- Excellent insulating performance
- Excellent thermal stability
- Low heat storage
- Resistance to thermal shock
- Good machinability

APPLICATIONS

- Back up insulation in refractory construction
- High temperature ceramic kiln & cars
- Hot face lining material in furnace building
- Back up insulation in steel ladles
- Back up insulation in Glass melting furnace
- Molten aluminium handling applications

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MAIN PROPERTIES

Physical Properties	M – 1600 ° C	L – 1600 ° C
Classification temperature° C	1600 ° C	1600 ° C
Chemical composition (%) (IS : 12107 / XRF)		
Al ₂ O ₃	> 70 *	> 40
SiO ₂	< 28	< 48
ZrO ₂		> 9
Loss on ignition %	< 10	< 10
Density (Nominal) kg/m ³	425	200
Modulus of Rupture Kpa upto 25mm thick	1600	500
Modulus of Rupture Kpa > 25mm thick	1000	250
Linear shrinkage % - 24 hrs (Max)	0.5 (At 1400°C)	2.0 (At 1400°C)
Thermal conductivity (W/mk) 600°C (Mean temperature) (ASTM C 201)	0.080	0.080
Availability & Packaging 500 mm width x 1000 mm length		
Thickness (mm)		
10	✓	✓
12	✓	✓
15	✓	✓
20	✓	✓
25	✓	✓
30	✓	✓
40	✓	✓
50	✓	✓

* Al₂O₃ + ZrO₂

All above boards are subjected to standard tolerances. The values given herein are typical values obtained in accordance with accepted test methods and subject to normal manufacturing variations. They are supplied as a technical service and are subject to change without notice. Therefore, the data contained herein should not be used for specification purposes.